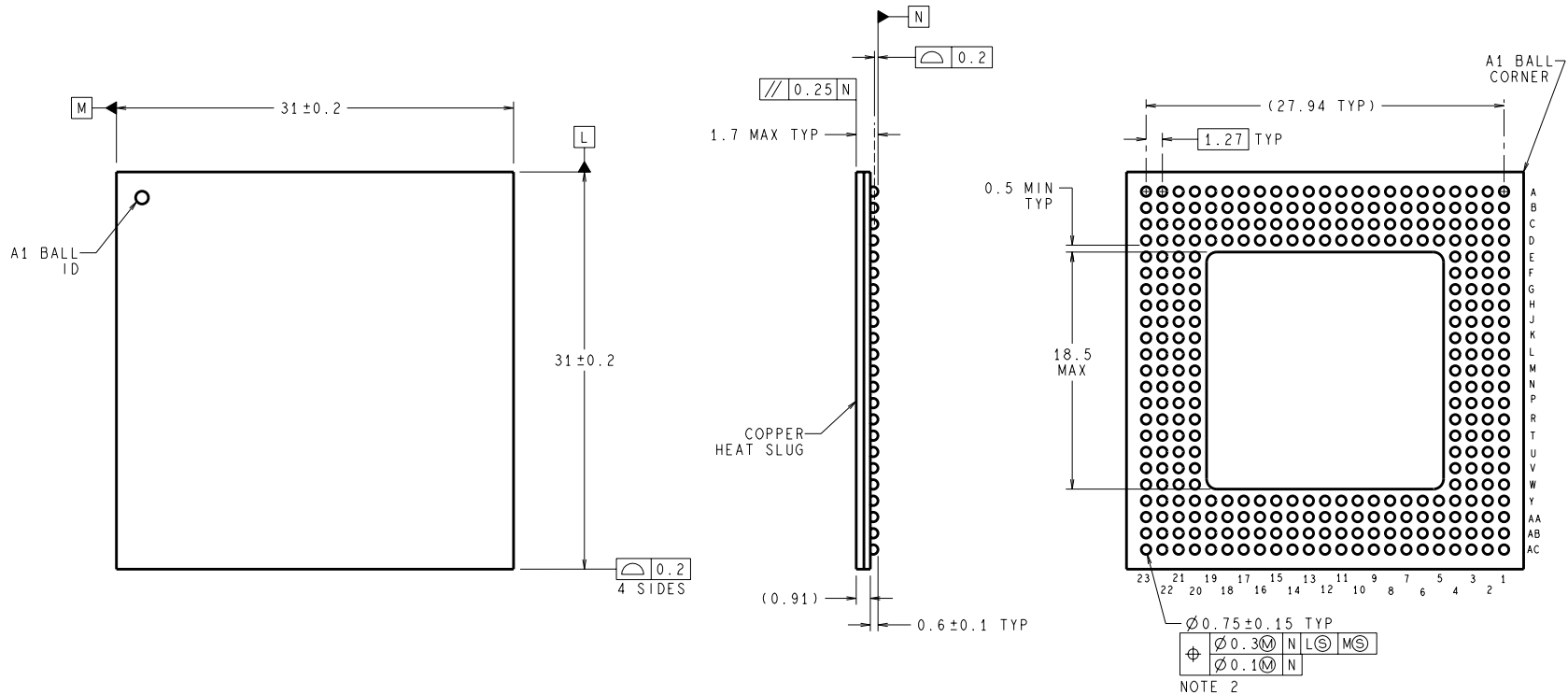


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12119	03/04/1999	MS/



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
- DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
- REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.27, DATED JUNE 1997.

APPROVALS	DATE	National Semiconductor			
DRAWN MARTA SUCHY	03/04/1999	2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DFTG. CHK.		SBGA, 31 X 31 X 1.7mm, 304 BALL, 1.27mm PITCH			
ENGR. CHK.					
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-UGB304A	A
INCH (MM)		DO NOT SCALE DRAWING		SHEET 1 of 1	